

DATA SHEET

TDA8758

**YC 8-bit low-power
analog-to-digital video interface**

Product specification
Supersedes data of 1995 Mar 22
File under Integrated Circuits, IC02

1996 Feb 01

YC 8-bit low-power analog-to-digital video interface

TDA8758

FEATURES

- Two 8-bit ADCs:
 - one Luminance or CVBS channel
 - one Chrominance channel
- Sampling rate up to 32 MHz
- Binary or two's complement 3-state TTL outputs for each channel
- Internal reference voltage regulator
- TTL-compatible digital inputs and outputs
- Power dissipation of 530 mW (typical)
- Input selector circuit (five selectable video inputs for CVBS or YC processing)
- Peak white enable input
- Clamp and Automatic Gain Control (AGC) functions for Y/CVBS channel (clamping on code 64 and Peak White level control at code 255)
- Clamp function for C channel (code 128)
- No sample-and-hold circuit required.

APPLICATIONS

- Video signal decoding
- Digital picture processing
- Frame grabbing
- Multimedia with the Philips Desktop Video chip set (and especially SAA7196 multistandard decoder and scaler).

GENERAL DESCRIPTION

The TDA8758 is an 8-bit video high-speed low-power analog-to-digital conversion (ADC) interface for YC and CVBS signal processing. It converts 1-of-3 CVBS input signals or 1-of-2 YC input signals into binary or two's complement words at a sampling rate of 32 MHz. All analog signal inputs are digitally clamped and an ADC interface is provided on the Y/CVBS channel. A fast precharge on clamp and AGC is provided for start-up. All digital inputs and outputs are TTL compatible.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CCA}	analog supply voltage		4.75	5.0	5.25	V
V _{CCD}	digital supply voltage		4.75	5.0	5.25	V
V _{CCO}	output stages supply voltage		4.75	5.0	5.25	V
I _{CCA}	analog supply current		–	59	70	mA
I _{CCD}	digital supply current		–	28	40	mA
I _{CCO}	output supply current	C _L = 15 pF	–	19	28	mA
ILE	DC integral linearity error		–	±0.75	±1.5	LSB
DLE	DC differential linearity error		–	±0.4	±1.0	LSB
EB	effective bits (from video input to digital outputs)	f _{clk} = 32 MHz; f _i = 4.43 MHz	–	7.1	–	bits
f _{clk(max)}	maximum clock frequency		30	32	–	MHz
B	maximum –3 dB bandwidth (input preamplifier)	full-scale; 0 dB gain	–	15	–	MHz
α _{ct}	crosstalk between Y and C channels and each video input		–	–63	–55	dB
P _{tot}	total power dissipation		–	530	724	mW

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA8758G	LQFP48	plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

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BLOCK DIAGRAM

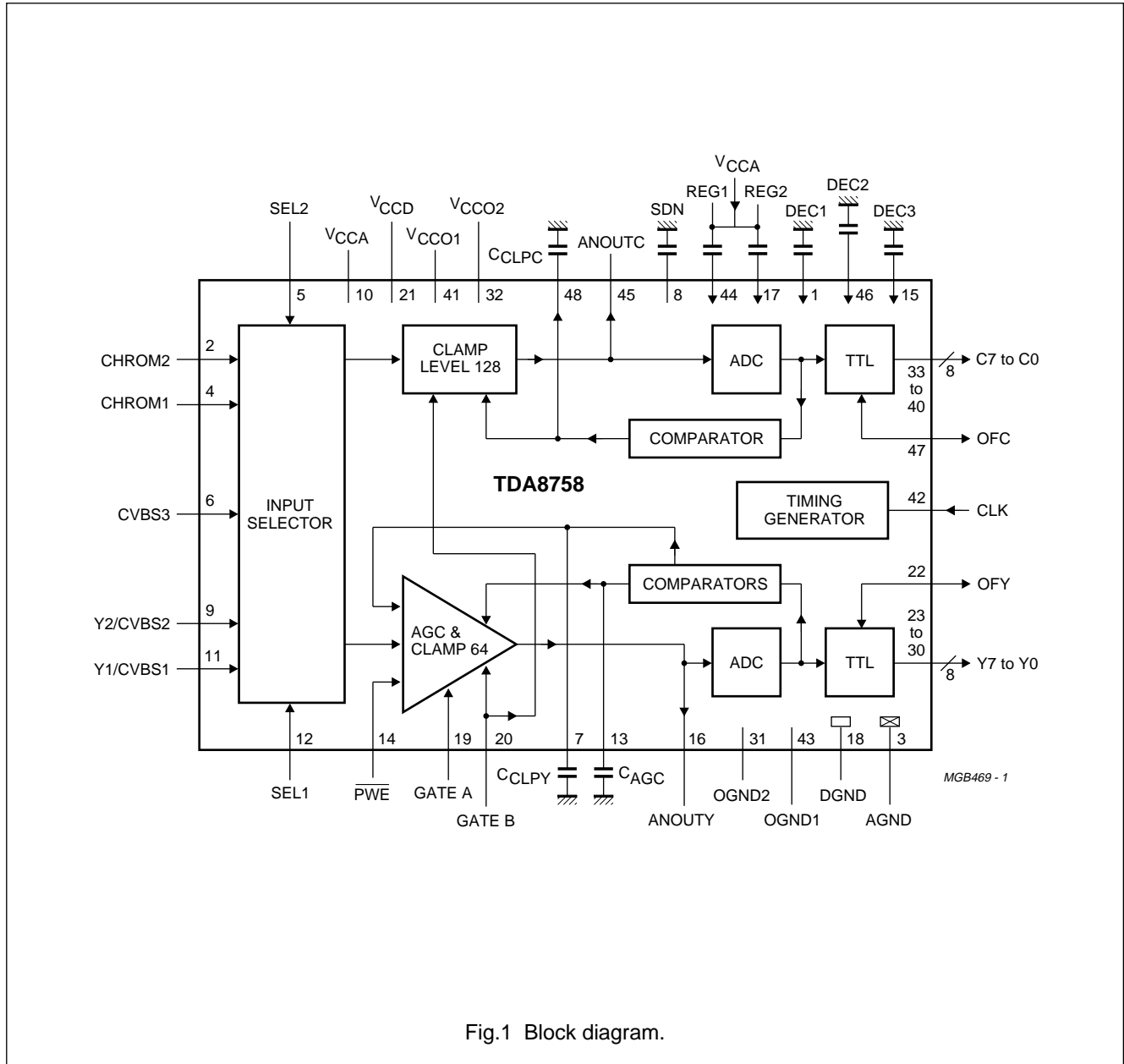


Fig.1 Block diagram.

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PINNING

SYMBOL	PIN	DESCRIPTION
DEC1	1	decoupling input 1
CHROM2	2	chrominance analog voltage input 2
AGND	3	analog ground
CHROM1	4	chrominance analog voltage input 1
SEL2	5	selection control input 2
CVBS3	6	luminance analog voltage input 3
CCLPY	7	Y channel clamping capacitor
SDN	8	stabilizer decoupling node
Y2/CVBS2	9	luminance analog voltage input 2
V _{CCA}	10	analog supply voltage (+5 V)
Y1/CVBS1	11	luminance analog voltage input 1
SEL1	12	selection control input 1
C _{AGC}	13	AGC capacitor
PWE	14	peak white enable input (active LOW)
DEC3	15	decoupling input 3
ANOUTY	16	analog output for Y channel
REG2	17	decoupling input 2 (internal stabilization loop decoupling)
DGND	18	digital ground
GATE A	19	AGC control input
GATE B	20	clamp control input
V _{CCD}	21	digital supply voltage (+5 V)
OFY	22	Y channel output format/chip enable (3-state input)
Y7	23	Y channel data output; bit 7 (MSB)
Y6	24	Y channel data output; bit 6
Y5	25	Y channel data output; bit 5
Y4	26	Y channel data output; bit 4
Y3	27	Y channel data output; bit 3
Y2	28	Y channel data output; bit 2
Y1	29	Y channel data output; bit 1
Y0	30	Y channel data output; bit 0 (LSB)
OGND2	31	output ground 2
V _{CCO2}	32	output supply voltage 2 (+5 V)
C7	33	C channel data output; bit 7 (MSB)
C6	34	C channel data output; bit 6
C5	35	C channel data output; bit 5
C4	36	C channel data output; bit 4
C3	37	C channel data output; bit 3
C2	38	C channel data output; bit 2
C1	39	C channel data output; bit 1
C0	40	C channel data output; bit 0 (LSB)

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SYMBOL	PIN	DESCRIPTION
V _{CCO1}	41	output supply voltage 1 (+5 V)
CLK	42	clock input
OGND1	43	output ground 1
REG1	44	decoupling input 1 (internal stabilization loop decoupling)
ANOUTC	45	analog output for C channel
DEC2	46	decoupling input 2
OFC	47	C channel output format/chip enable (3-state input)
C _{CLPC}	48	C channel clamping capacitor

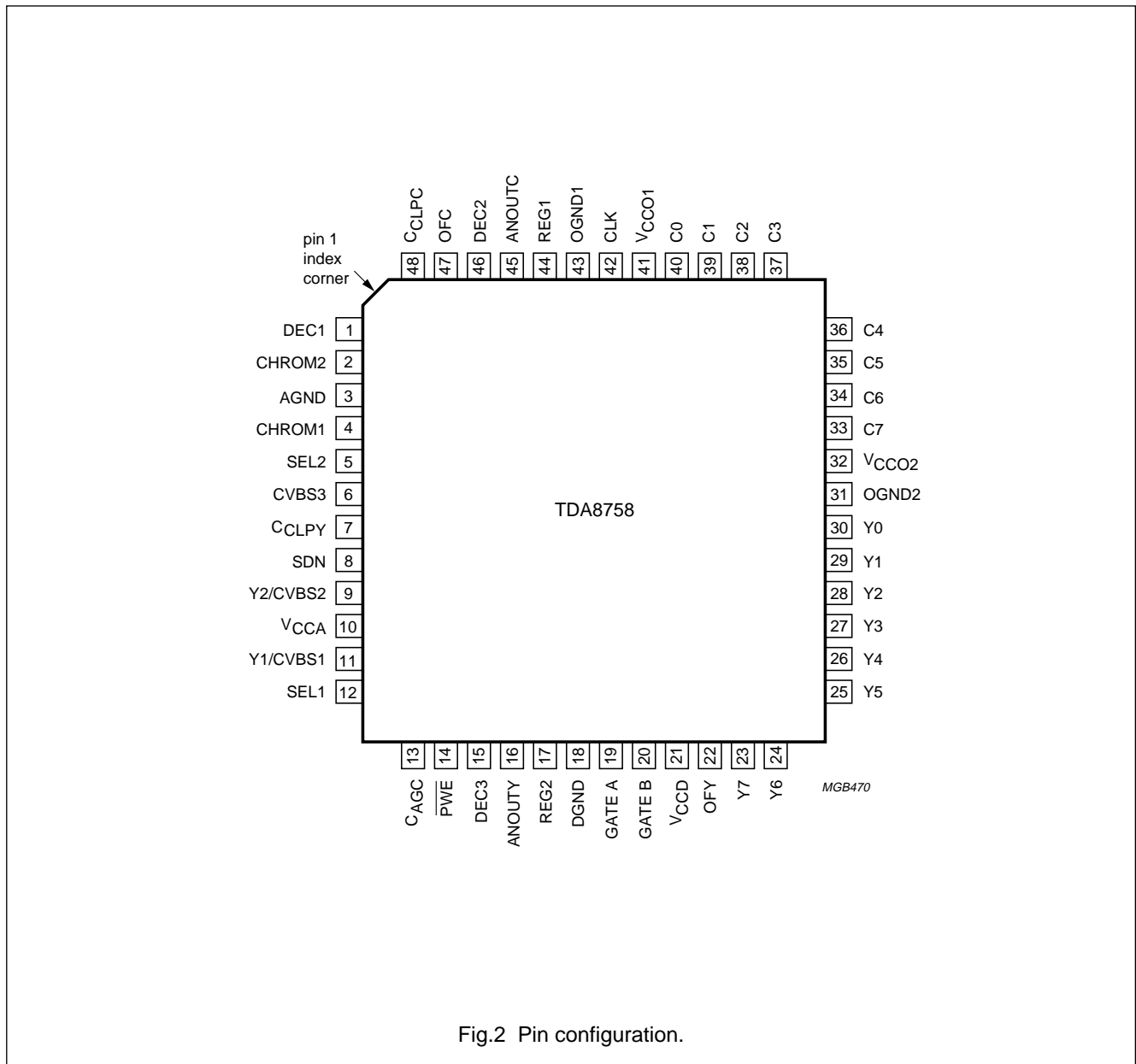


Fig.2 Pin configuration.

YC 8-bit low-power analog-to-digital video interface

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FUNCTIONAL DESCRIPTION

The TDA8758 provides a simple interface between CVBS or Y/C analog signals and a digital colour decoder.

Video inputs selection

The input selector allows a choice from different video sources, and has one of the following configurations:

- A: Two Y/C and one CVBS signals
- B: One Y/C and two CVBS signals
- C: Three CVBS signals (only the Y channel is used).

The wiring of the five video inputs (pins 2, 4, 6, 9 and 11) and the control of the two selection inputs (pins 5 and 12) will depend on the available video sources.

- In configuration A, connect as follows:
 - Y1 to pin 11
 - C1 to pin 4
 - Y2 to pin 9
 - C2 to pin 2
 - CVBS3 to pin 6.

Keep SEL2 (pin 5) LOW and select Y1/C1 or Y2/C2 by switching SEL1 (pin 12).

CVBS3 is selected with SEL1 and SEL2 HIGH.

- In configuration B, replace Y1 (or Y2) by a CVBS input (no more C1 or C2). The selection mode is the same.
- In configuration C, connect as follows:
 - CVBS1 to pin 11
 - CVBS2 to pin 9
 - CVBS3 to pin 6.

Use both SEL1 and SEL2 to select inputs.

Remark: the video inputs selection is a static selection.

Synchronization pulses

GATE A and GATE B pulses are synchronization pulses occurring during the sync period and rear porch respectively. They should be distinct.

On the Y channel, the digital output of the ADC is compared to internal digital reference levels. The resultant outputs control the charge or discharge current of a capacitor connected to the C_{AGC} pin. The voltage across this capacitor controls the gain of the video amplifier. This is the control loop.

The sync level comparator is active during a positive-going pulse at the GATE A input. This means that sync pulse of the composite video signal is used as an amplitude reference. The bottom of the sync pulse is adjusted to obtain a digital output of logic 1 at the converter Y output. As the black level is digital level 64, the sync pulse will have a digital amplitude of 64 LSBs.

The Peak White control loop is active when the selection pin PWE is LOW. Then, if the Y video signal exceeds the digital code of 255, it will be limited to avoid any over-range of the converter.

The clamp level control is accomplished by using the same techniques as used for the gain control. On both Y and C channels, the black level digital comparators are active during a positive-going pulse at the GATE B input. On the Y channel, the clamping capacitor connected to the C_{CLPY} pin will be charged or discharged to adjust the digital output to code 64. On the C channel, the clamping capacitor connected to the C_{CLPC} pin will be charged or discharged to adjust the digital output to code 128.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CCA}	analog supply voltage		-0.3	+7.0	V
V_{CCD}	digital supply voltage		-0.3	+7.0	V
V_{CCO}	output supply voltage		-0.3	+7.0	V
ΔV_{CC}	supply voltage difference between V_{CCA} and V_{CCD}		-1.0	+1.0	V
	supply voltage difference between V_{CCO} and V_{CCD}		-1.0	+1.0	V
	supply voltage difference between V_{CCA} and V_{CCO}		-1.0	+1.0	V
V_I	input voltage	referenced to AGND	-	5.0	V
$V_{clk(p-p)}$	AC input voltage for switching (peak-to-peak value)	referenced to DGND	-	V_{CCO}	V
I_O	output current		-	+6	mA
T_{stg}	storage temperature		-55	+150	°C
T_{amb}	operating ambient temperature		0	+70	°C
T_j	junction temperature		-	+150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient in free air	72	K/W

CHARACTERISTICS

$V_{CCA} = V_{10}$ to $V_3 = 4.75$ to 5.25 V; $V_{CCD} = V_{21}$ to $V_{18} = 4.75$ to 5.25 V; $V_{CCO1} = V_{41}$ to $V_{43} = 4.75$ to 5.25 V; $V_{CCO2} = V_{32}$ to $V_{31} = 4.75$ to 5.25 V; AGND and DGND shorted together; V_{CCA} to $V_{CCD} = -0.25$ to $+0.25$ V; V_{CCO} to $V_{CCD} = -0.25$ to $+0.25$ V; V_{CCA} to $V_{CCO} = -0.25$ to $+0.25$ V; $T_{amb} = 0$ to $+70$ °C; typical values measured at $V_{CCA} = V_{CCD} = V_{CCO} = 5$ V and $T_{amb} = 25$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies						
V_{CCA}	analog supply voltage		4.75	5.0	5.25	V
V_{CCD}	digital supply voltage		4.75	5.0	5.25	V
V_{CCO}	output stages supply voltage		4.75	5.0	5.25	V
I_{CCA}	analog supply current		-	59	70	mA
I_{CCD}	digital supply current		-	28	40	mA
I_{CCOtot}	total output supply current	$C_L = 15$ pF	-	19	28	mA
Video amplifier inputs						
Y1/CVBS1, Y2/CVBS2, CVBS3, CHROM1 AND CHROM2 INPUTS						
$V_{I(p-p)}$	input voltage (peak-to-peak value)	AGC load with external capacitor; note 1				
	Y channel		0.7	-	1.4	V
	C channel		-	1.0	-	V
$ Z_i $	input impedance	$f_i = 6$ MHz	-	25	-	k Ω
C_i	input capacitance	$f_i = 6$ MHz	-	2	-	pF

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
SEL1 AND SEL2 TTL INPUTS; see Table 1						
V_{IL}	LOW level input voltage		0	–	0.8	V
V_{IH}	HIGH level input voltage		2.0	–	V_{CCD}	V
I_{IL}	LOW level input current	$V_I = 0.4\text{ V}$	–400	–	–	μA
I_{IH}	HIGH level input current	$V_I = 2.7\text{ V}$	–	–	20	μA
GATE A AND GATE B TTL INPUTS; see Figs 5 and 6						
V_{IL}	LOW level input voltage		0	–	0.8	V
V_{IH}	HIGH level input voltage		2.0	–	V_{CCD}	V
I_{IL}	LOW level input current	$V_I = 0.4\text{ V}$	–400	–	–	μA
I_{IH}	HIGH level input current	$V_I = 2.7\text{ V}$	–	–	20	μA
AGC INPUT (PIN 13); see Fig.8						
$V_{13(\text{min})}$	AGC voltage for minimum gain at –3 dB		–	3.3	–	V
$V_{13(\text{max})}$	AGC voltage for maximum gain at +3 dB		–	3.75	–	V
I_{12}	AGC output current		see Table 2			
C-CHANNEL CLAMP INPUT (PIN 48)						
V_{48}	CLAMP voltage for code 128 output		–	3.45	–	V
I_{48}	CLAMP output current		see Table 3			
Y-CHANNEL CLAMP INPUT (PIN 7)						
V_7	CLAMP voltage for code 64 output		–	3.70	–	V
I_7	CLAMP output current		see Table 3			
Video amplifier dynamic characteristics						
α_{ct}	crosstalk between video inputs (pins 2, 4, 6, 9 and 11)	$V_{CCA} = 4.75\text{ to }5.25\text{ V}$	–	–63	–55	dB
B	–3 dB bandwidth		–	15	–	MHz
ΔG	gain range		–3	–	+3	dB
G_{stab}	gain stability as a function of: supply voltage supply voltage and temperature	$f_i = 4.43\text{ MHz}$	–	–	0.5	%
			–	–	6	%
Analog-to-digital converter inputs						
CLK INPUT (PIN 42)						
V_{IL}	LOW level input voltage		0	–	0.8	V
V_{IH}	HIGH level input voltage		2.0	–	V_{CCD}	V
I_{IL}	LOW level input current	$V_{clk} = 0.4\text{ V}$	–400	–	–	μA
I_{IH}	HIGH level input current	$V_{clk} = 2.7\text{ V}$	–	–	20	μA
C_I	input capacitance	$f_{clk} = 32\text{ MHz}$	–	2	–	pF

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
OFY AND OFC INPUTS; 3-STATE; see Table 4						
V _{IL}	LOW level input voltage		0	–	0.2	V
V _{IH}	HIGH level input voltage		2.6	–	V _{CCD}	V
V _I	input voltage in high impedance state		–	1.15	–	V
I _{IL}	LOW level input current		–370	–300	–	μA
I _{IH}	HIGH level input current		–	500	700	μA
Analog-to-digital converter outputs						
ANOUTY AND ANOUTC OUTPUTS (PINS 16 AND 45); see Table 5						
V _{ANOUT}	output voltage	digital output = 00	–	2.6	–	V
V _{ANOUT}	output voltage	digital output = 255	–	3.6	–	V
V _{ANOUT(p-p)}	output voltage amplitude (peak-to-peak value)		–	1.0	–	V
DIGITAL OUTPUTS Y0 TO Y7, C0 TO C7						
V _{OL}	LOW level output voltage	I _{OL} = 2 mA	0	–	0.6	V
V _{OH}	HIGH level output voltage	I _{OL} = –0.4 mA	2.4	–	V _{CCD}	V
Switching characteristics; see Fig.9						
f _{clk(max)}	CLK input maximum frequency	note 2	30	32	–	MHz
t _{CPH}	clock pulse width HIGH		12	–	–	ns
t _{CPL}	clock pulse with LOW		12	–	–	ns
Analog signal processing from video input to digital output on both channels; 0 dB gain (f_{clk} = 32 MHz)						
INL	DC integral non-linearity		–	±0.75	±1.5	LSB
DNL	DC differential non-linearity		–	±0.4	±1.0	LSB
AINL	AC integral non linearity	f _i = 4.43 MHz	–	±1.5	–	LSB
ADNL	AC differential non-linearity	f _i = 4.43 MHz	–	±0.5	–	LSB
THD	total harmonic distortion	note 3	–	–52	–	dB
EB	effective bits	f _i = 4.43 MHz; note 4	–	7.1	–	bits
G _{diff}	differential gain	V _{16,45} = 1.0 V (p-p); see Fig.4; PAL modulated ramp; note 5	–	1.5	3.0	%
φ _{diff}	differential phase	see Fig.5; PAL modulated ramp; note 5	–	0.6	1.5	deg
SVRR2	supply voltage ripple rejection	note 6	–	–	5	%/V

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Timing ($f_{clk} = 32$ MHz); see Fig.9						
DIGITAL OUTPUTS ($C_L = 15$ pF)						
t_{ds}	sampling delay time		–	2	–	ns
t_h	output hold time		10	–	–	ns
t_d	output delay time		–	15	18	ns
t_W	clamp pulse width	see Figs 6 and 7	2	3	–	μ s
3-state output delay times; see Fig.10						
t_{dZH}	enable HIGH		–	12	14	ns
t_{dZL}	enable LOW		–	10	12	ns
t_{dHZ}	disable HIGH		–	58	62	ns
t_{dLZ}	disable LOW		–	70	74	ns

Notes

- 0 dB is obtained at the AGC amplifier when applying $V_{I(p-p)} = 1.0$ V on Y channel.
- It is recommended that the rise and fall times of the clock are ≥ 1 ns. In addition, a 'good layout' for the digital and analog grounds is recommended.
- THD (total harmonic distortion) is obtained with the addition of the first five harmonics:

$$THD = 20 \log \frac{F}{\sqrt{(2nd)^2 + (3rd)^2 + (4th)^2 + (5th)^2 + (6th)^2}}$$

a) F being the fundamental harmonic referenced at 0 dB for a full-scale sine wave input.

- Effective bits are obtained via a Fast Fourier Transform (FFT) treatment taking 8 K acquisition points per equivalent fundamental period. The calculation takes into account all harmonics and noise up to half of the clock frequency (NYQUIST frequency). Conversion to signal-to-noise ratio: $S/N = EB \times 6.02 + 1.76$ dB.
- Measurement carried out using video analyser VM700A, where video analog signal is reconstructed through a digital-to-analog converter.
- The supply voltage ripple rejection is the relative variation of the analog signal (full-scale signal at input) for 0.5 V of supply variation:

$$SVRR2 = \frac{\Delta(V_{I(00)} - V_{I(FF)}) \times (V_{I(00)} - V_{I(FF)})}{\Delta V_{CCA}}$$

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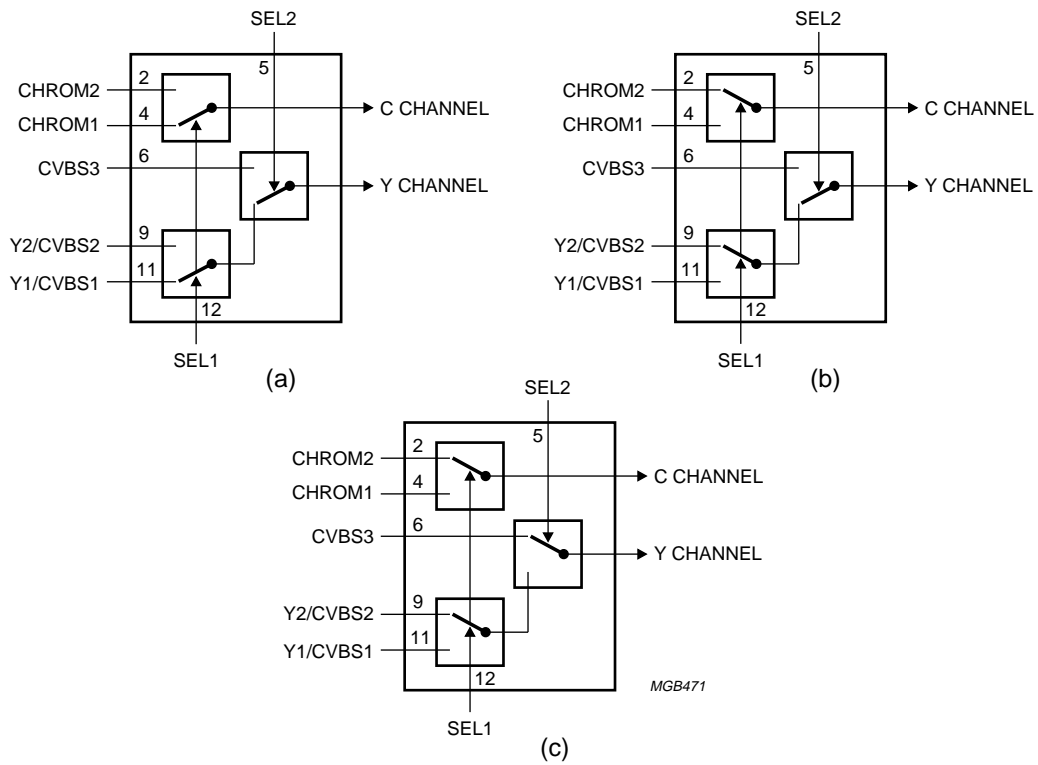


Fig.3 Video inputs selector.

Table 1 Video input selection

SEL1	SEL2	Y-CHANNEL	C-CHANNEL	FIGURE 3
0	X ⁽¹⁾	Y1/CVBS1	CHROM1	(a)
1	0	Y2/CVBS2	CHROM2	(b)
1	1	CVBS3	CHROM2	(c)

Note

1. X = don't care.

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Table 2 AGC output current

$\overline{\text{PWE}}$	GATE A	DIGITAL OUTPUT	I_{AGC}
0	0	output < 255	0 μA
		output > 255	+540 μA
0	1	output < 0	+8 μA
		0 < output < 255	-8 μA
		output > 255	+540 μA
1	0	X ⁽¹⁾	0 μA
1	1	output < 0	+8 μA
		0 < output < 255	-8 μA

Note

- 1. X = don't care.

Table 3 CLAMP output current

CLAMP	GATE B	DIGITAL OUTPUT	I_{CLAMP}
C	1	output < 128	+54 μA
		output > 128	-54 μA
X ⁽¹⁾	0	X ⁽¹⁾	0 μA
Y	1	output < 64	+54 μA
		64 < output	-54 μA

Note

- 1. X = don't care.

Table 5 Output coding and ANOUTY (or ANOUTC) voltage (typical values)

STEP	V_i	BINARY OUTPUTS								TWS COMPLIMENT							
		D7	D6	D5	D4	D3	D2	D1	D0	D7	D6	D5	D4	D3	D2	D1	D0
Underflow	-	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
0	2.6	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
1	-	0	0	0	0	0	0	0	1	1	0	0	0	0	0	0	1
.	-
.	-
254	-	1	1	1	1	1	1	1	0	0	1	1	1	1	1	1	0
255	3.6	1	1	1	1	1	1	1	1	0	1	1	1	1	1	1	1
Overflow	-	1	1	1	1	1	1	1	1	0	1	1	1	1	1	1	1

Table 4 OFY and OFC input coding

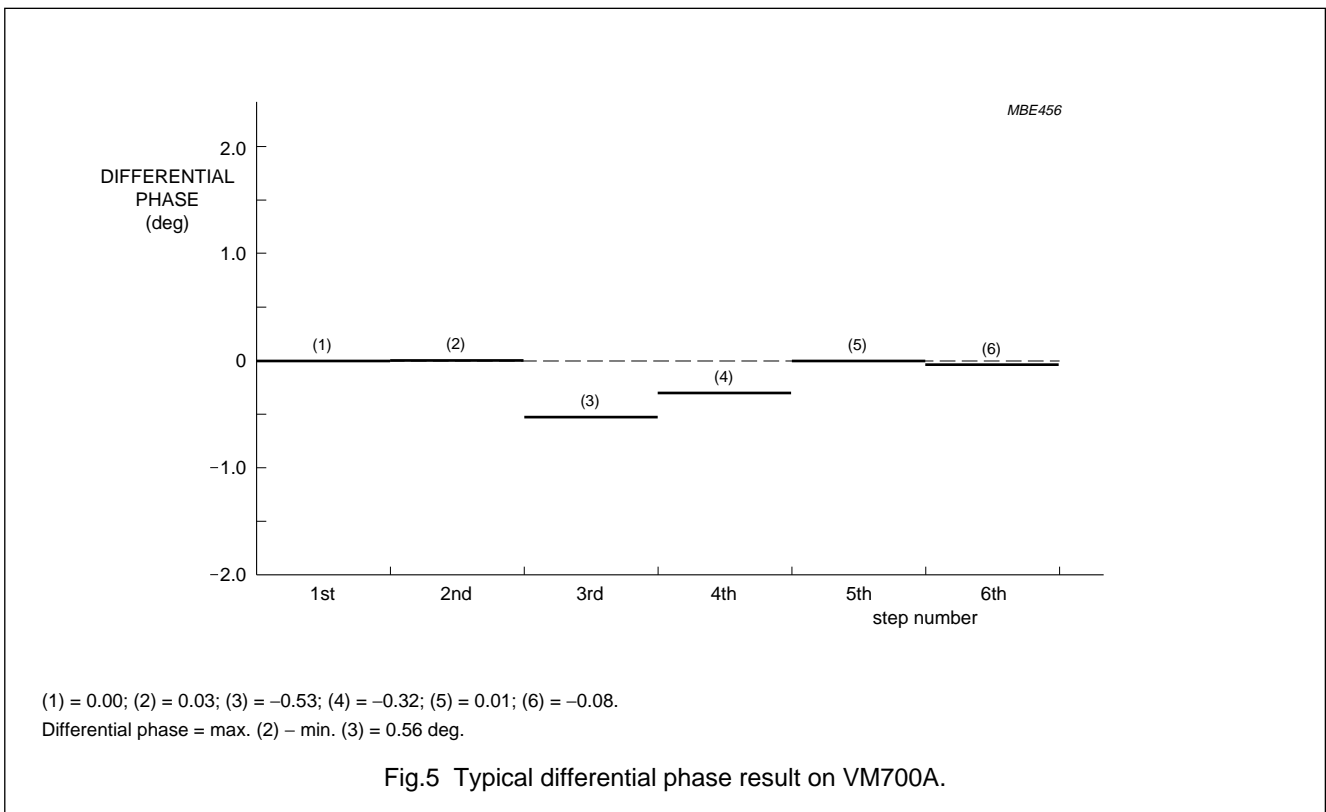
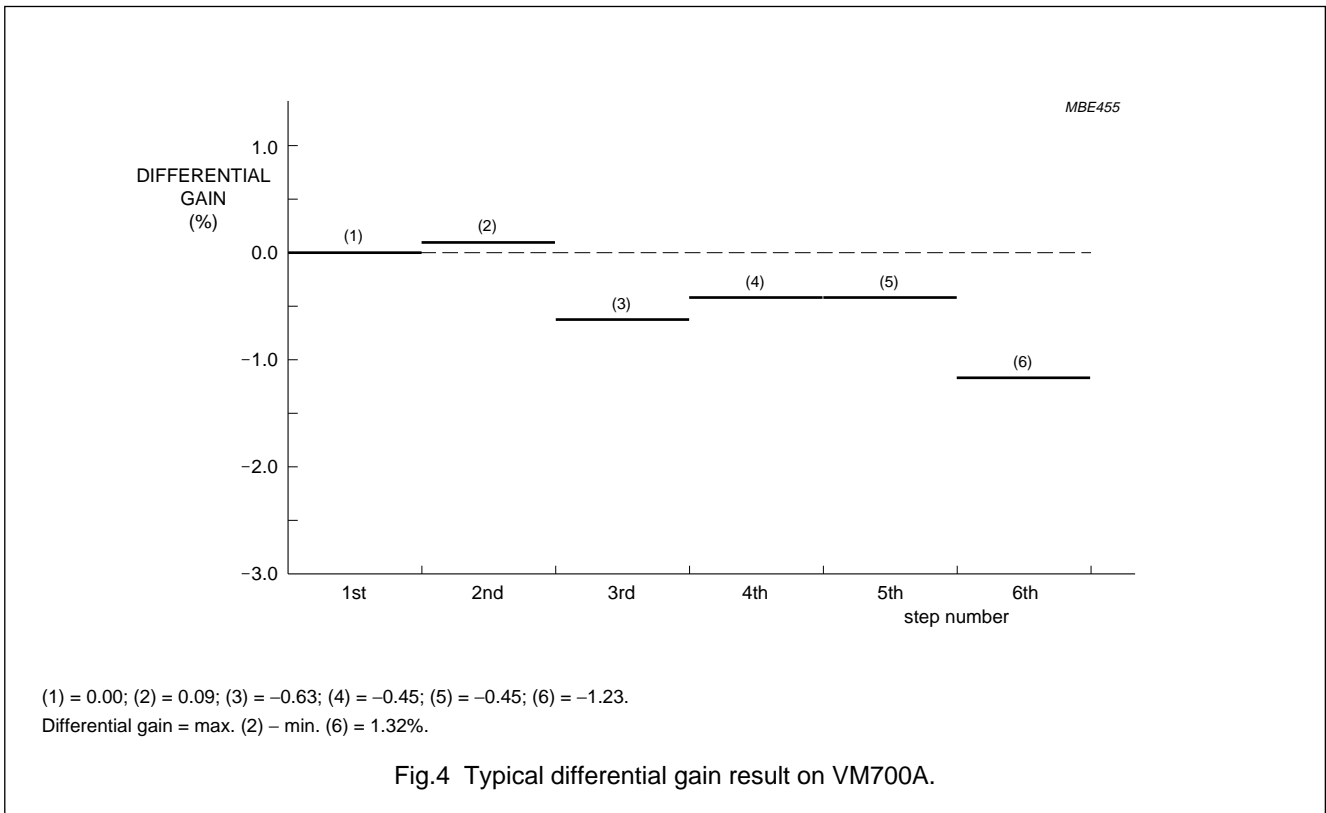
OFY (or OFC)	Y0 to Y7 (or C0 TO C7)
0	active, twos complement
1	high impedance
open circuit ⁽¹⁾	active, binary

Note

- 1. Use C \geq 10 pF to DGND.

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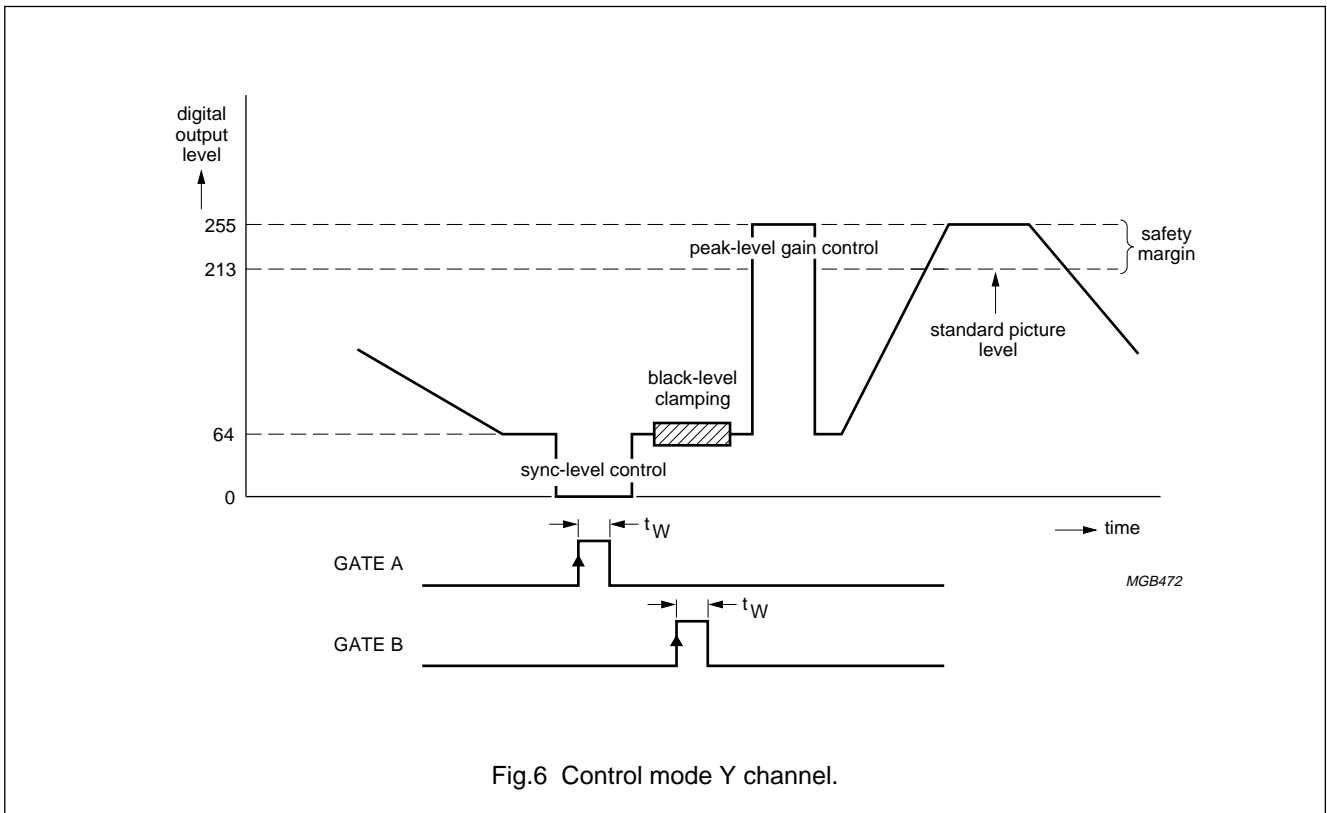


Fig.6 Control mode Y channel.

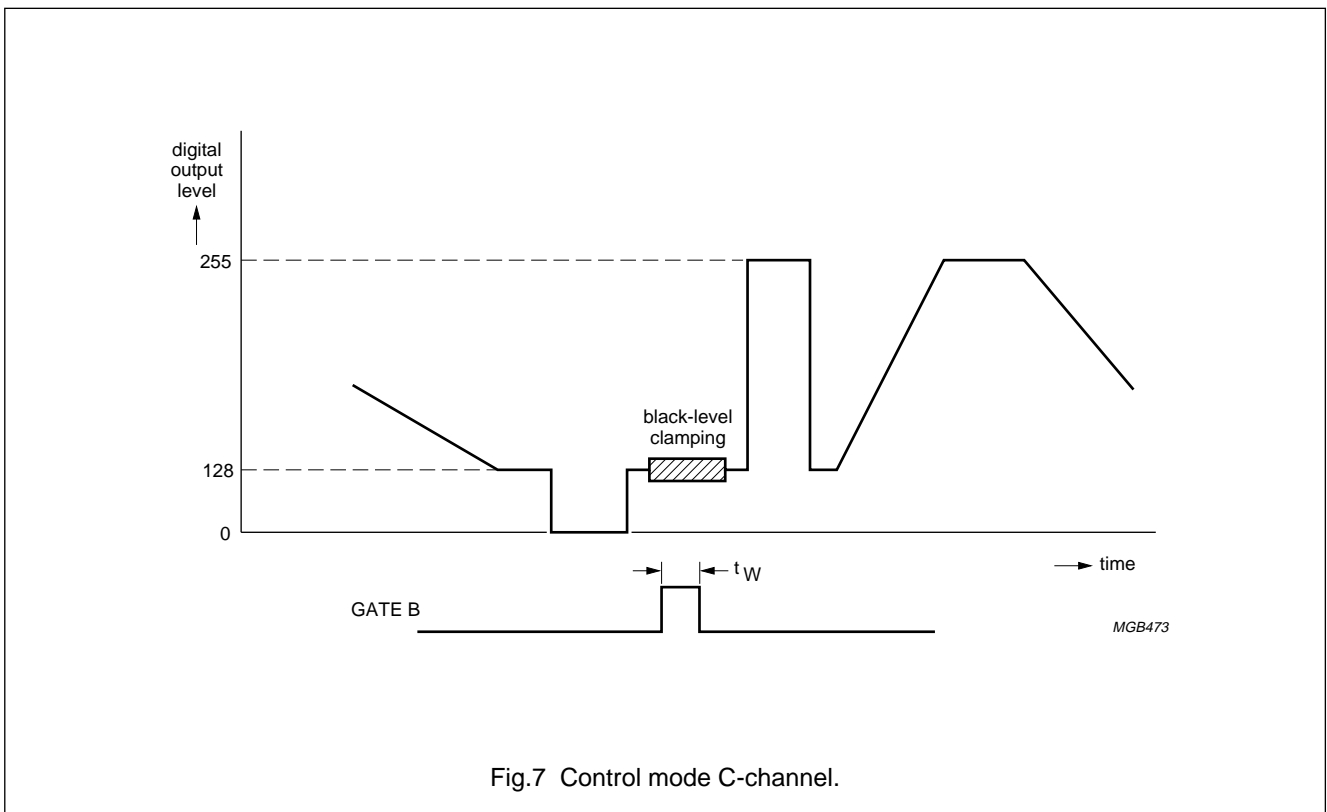
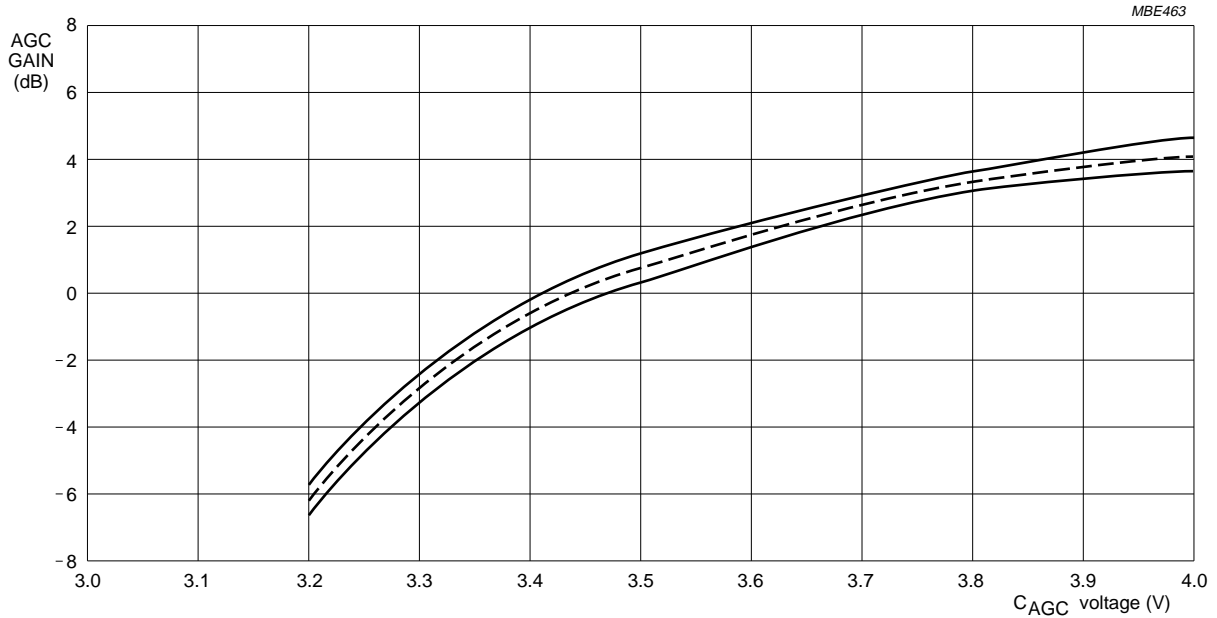


Fig.7 Control mode C-channel.

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Dotted line: Typical curve ($T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CC} = 5\text{ V}$).
 Full line: Maximum envelope ($T_{amb} = 0\text{ to }70\text{ }^{\circ}\text{C}$; $V_{CC} = 4.75\text{ to }5.25\text{ V}$).

Fig.8 AGC behaviour as a function temperature and supply voltage for ANOUTY output; $f_i = 4.43\text{ MHz}$, $V_i = 0\text{ dB}$.

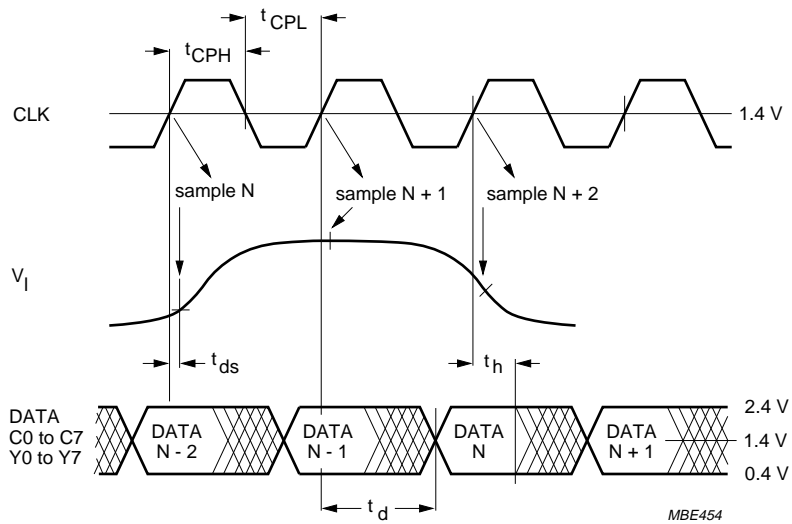
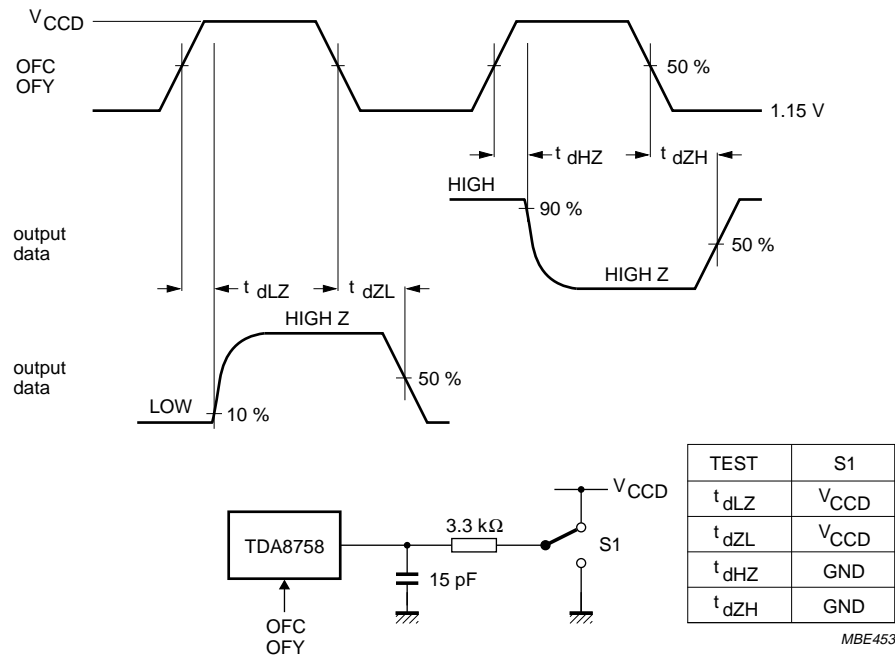


Fig.9 Timing diagram.

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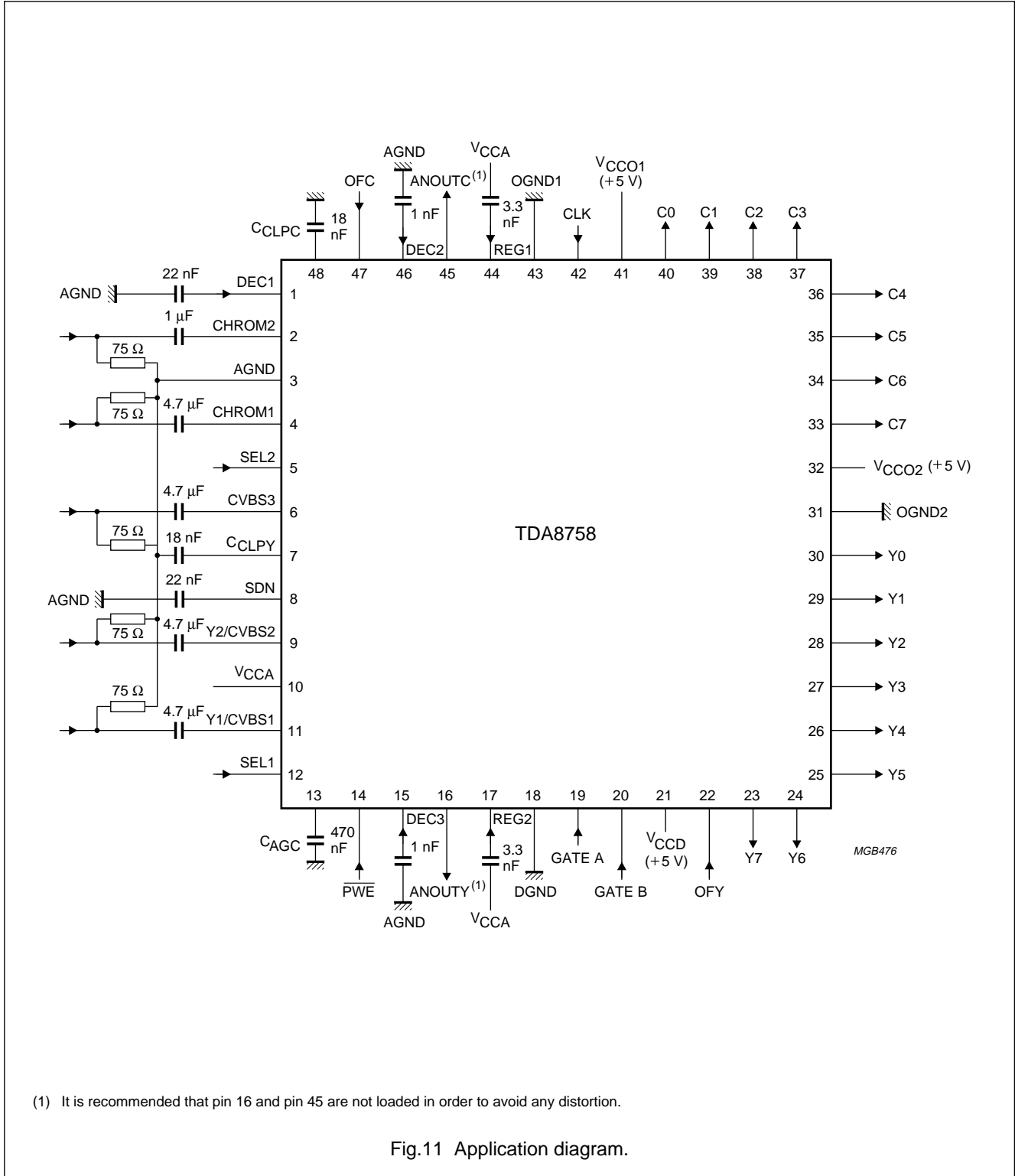
$f_{OFC} = f_{OFY} = 100 \text{ kHz}$.

Fig.10 Timing diagram and test conditions of 3-state output delay time.

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APPLICATION INFORMATION



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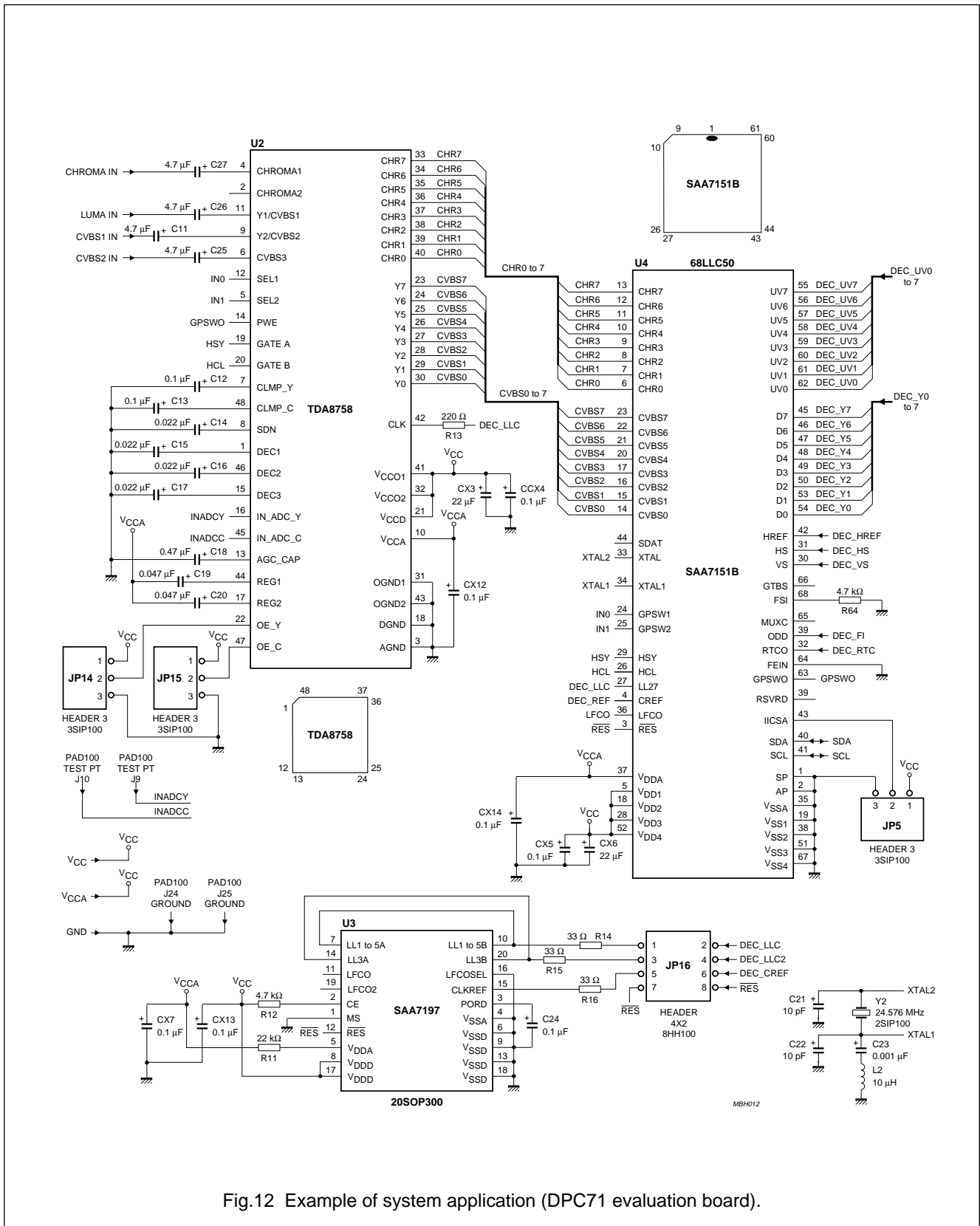


Fig.12 Example of system application (DPC71 evaluation board).

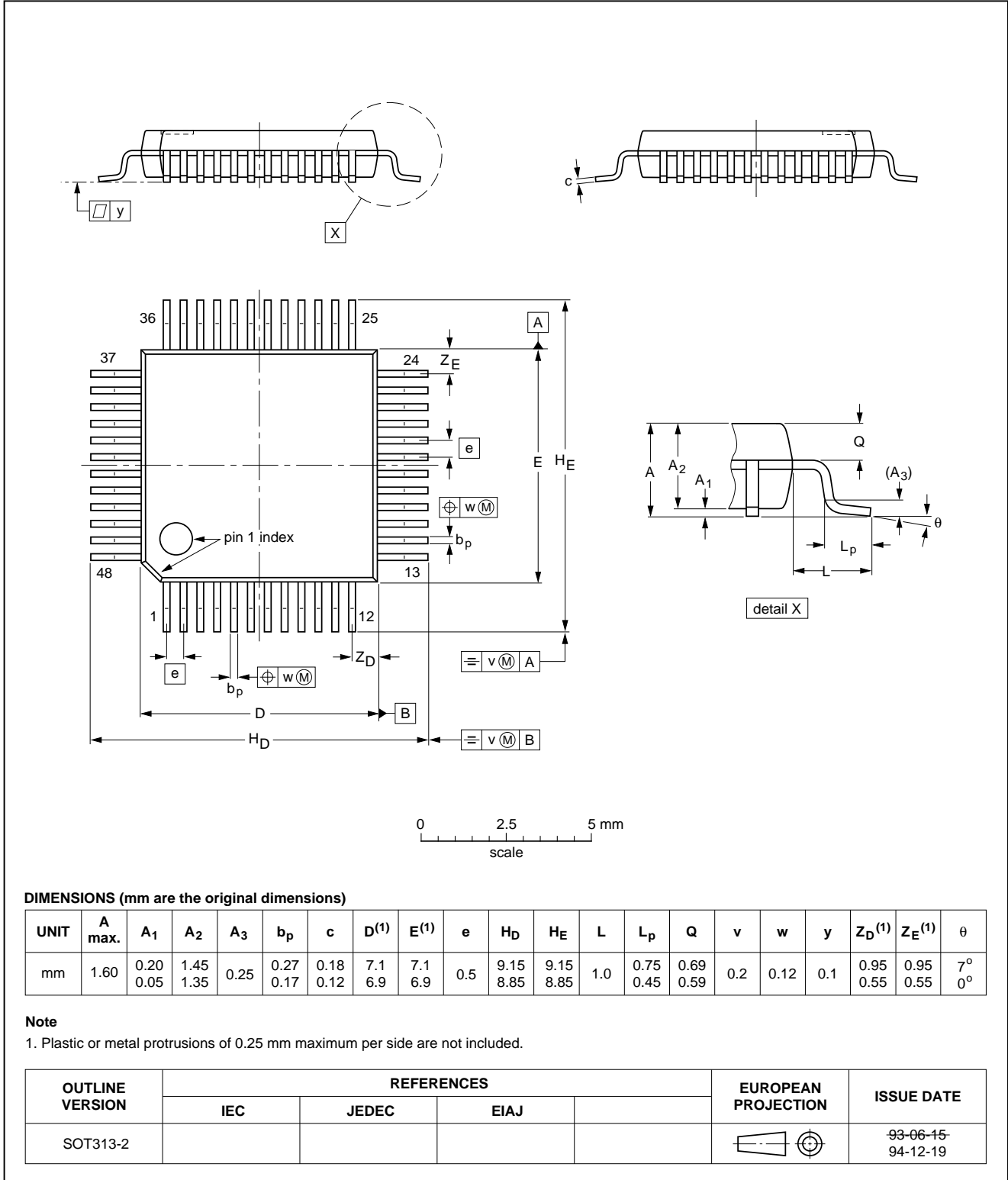
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PACKAGE OUTLINE

LQFP48: plastic low profile quad flat package; 48 leads; body 7 x 7 x 1.4 mm

SOT313-2



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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all LQFP packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering is **not** recommended for LQFP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

If wave soldering cannot be avoided, the following conditions must be observed:

- **A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.**
- **The footprint must be at an angle of 45° to the board direction and must incorporate solder thieves downstream and at the side corners.**

Even with these conditions, do not consider wave soldering LQFP packages LQFP48 (SOT313-2), LQFP64 (SOT314-2) or LQFP80 (SOT315-1).

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

YC 8-bit low-power analog-to-digital video interface

TDA8758

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
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NOTES

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NOTES

Philips Semiconductors – a worldwide company

Argentina: IEROD, Av. Juramento 1992 - 14.b, (1428)
BUENOS AIRES, Tel. (541)786 7633, Fax. (541)786 9367

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,
Tel. (02)805 4455, Fax. (02)805 4466

Austria: Triester Str. 64, A-1101 WIEN, P.O. Box 213,
Tel. (01)60 101-1236, Fax. (01)60 101-1211

Belgium: Postbus 90050, 5600 PB EINDHOVEN, The Netherlands,
Tel. (31)40-2783749, Fax. (31)40-2788399

Brazil: Rua do Rocio 220 - 5th floor, Suite 51,
CEP: 04552-903-SÃO PAULO-SP, Brazil,
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China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. (852)2319 7888, Fax. (852)2319 7700

Colombia: IPRELENZO LTDA, Carrera 21 No. 56-17,
77621 BOGOTA, Tel. (571)249 7624/(571)217 4609,
Fax. (571)217 4549

Denmark: Prags Boulevard 80, PB 1919, DK-2300
COPENHAGEN S, Tel. (45)32 88 26 36, Fax. (45)31 57 19 49

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. (358)0-615 800, Fax. (358)0-61580 920

France: 4 Rue du Port-aux-Vins, BP317,
92156 SURESNES Cedex,
Tel. (01)4099 6161, Fax. (01)4099 6427

Germany: P.O. Box 10 51 40, 20035 HAMBURG,
Tel. (040)23 53 60, Fax. (040)23 53 63 00

Greece: No. 15, 25th March Street, GR 17778 TAVROS,
Tel. (01)4894 339/4894 911, Fax. (01)4814 240

India: Philips INDIA Ltd, Shivsagar Estate, A Block,
Dr. Annie Besant Rd. Worli, Bombay 400 018
Tel. (022)4938 541, Fax. (022)4938 722

Indonesia: Philips House, Jalan H.R. Rasuna Said Kav. 3-4,
P.O. Box 4252, JAKARTA 12950,
Tel. (021)5201 122, Fax. (021)5205 189

Ireland: Newstead, Clonskeagh, DUBLIN 14,
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Italy: PHILIPS SEMICONDUCTORS S.r.l.,
Piazza IV Novembre 3, 20124 MILANO,
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Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,
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Korea: Philips House, 260-199 Itaewon-dong,
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Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA,
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Mexico: 5900 Gateway East, Suite 200, EL PASO, TX 79905,
Tel. 9-5(800)234-7381, Fax. (708)296-8556

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. (040)2783749, Fax. (040)2788399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. (09)849-4160, Fax. (09)849-7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. (022)74 8000, Fax. (022)74 8341

Pakistan: Philips Electrical Industries of Pakistan Ltd.,
Exchange Bldg. ST-2/A, Block 9, KDA Scheme 5, Clifton,
KARACHI 75600, Tel. (021)587 4641-49,
Fax. (021)577035/5874546

Philippines: PHILIPS SEMICONDUCTORS PHILIPPINES Inc.,
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Portugal: PHILIPS PORTUGUESA, S.A.,
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Apartado 300, 2795 LINDA-A-VELHA,
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Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,
Tel. (65)350 2000, Fax. (65)251 6500

South Africa: S.A. PHILIPS Pty Ltd.,
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P.O. Box 7430, Johannesburg 2000,
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Spain: Balmes 22, 08007 BARCELONA,
Tel. (03)301 6312, Fax. (03)301 42 43

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Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. (01)488 2211, Fax. (01)481 77 30

Taiwan: PHILIPS TAIWAN Ltd., 23-30F, 66, Chung Hsiao West
Road, Sec. 1. Taipeh, Taiwan ROC, P.O. Box 22978,
TAIPEI 100, Tel. (886) 2 382 4443, Fax. (886) 2 382 4444

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong,
Bangkok 10260, THAILAND,
Tel. (66) 2 745-4090, Fax. (66) 2 398-0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,
Tel. (0212)279 27 70, Fax. (0212)282 67 07

Ukraine: Philips UKRAINE, 2A Akademika Koroleva str., Office 165,
252148 KIEV, Tel. 380-44-4760297, Fax. 380-44-4766991

United Kingdom: Philips Semiconductors LTD.,
276 Bath Road, Hayes, MIDDLESEX UB3 5BX,
Tel. (0181)730-5000, Fax. (0181)754-8421

United States: 811 East Arques Avenue, SUNNYVALE,
CA 94088-3409, Tel. (800)234-7381, Fax. (708)296-8556

Uruguay: Coronel Mora 433, MONTEVIDEO,
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For all other countries apply to: Philips Semiconductors,
International Marketing and Sales, Building BE-p,
P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands,
Telex 35000 phtcnl, Fax. +31-40-2724825

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